



Product Change Notification / JAON-04DXFD964

Date:

09-Feb-2021

Product Category:

8-bit Microcontrollers, Analog to Digital Converters, Capacitive Touch Sensors, Charge Pump DC-to-DC Converters, Digital Potentiometers, Digital to Analog Converters, Instrumentation Amplifier, Interface-Controller Area Network (CAN), Interface- Infrared Products, Interface- LIN Transceiver, KEELOQ® Encoder Devices, Linear Comparators, Linear Op Amps, Linear Programmable Gain Amplifiers, Memory, Piezoelectric Horn Drivers and CO Detector, Power Management - PWM Controllers, Power MOSFET Drivers, Real-Time Clock/Calendar, RFID tag ICs - microID® ICs, Temperature Sensors

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4541 Final Notice: Qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and gold (Au) bond wire material assembled at MMT assembly site.

Affected CPNs:

[JAON-04DXFD964_Affected_CPN_02092021.pdf](#)

[JAON-04DXFD964_Affected_CPN_02092021.csv](#)

Notification Text:

PCN Status: Final notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change: Qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and gold (Au) bond wire material assembled at MMT assembly site.

Pre Change:

Using lead frame without lead lock

Post Change:Using lead frame with lead lock

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	Microchip Technology Thailand (Branch) / MMT	Microchip Technology Thailand (Branch) / MMT
Wire material	Au	Au
Die attach material	8390A	8390A
Molding compound material	G600V	G600V
Lead frame material	CDA194	CDA194
Lead Frame Lead Lock	No	Yes
	See attached pre and post change comparison	

Impacts to Data Sheet: None

Change Impact:None

Reason for Change:To improve productivity by qualifying new lead frame design

Change Implementation Status:In Progress

Estimated First Ship Date:February 19, 2021 (date code: 2108)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Due to unforeseen circumstances, that are out of Microchip's control, full qualification will be made available as soon as it is approved which may be after the estimated first ship date so that Microchip can maintain continuity of supply and not disrupt customer orders.

Time Table Summary:

	February 2021				March 2021				
Workweek	06	07	08	09	10	11	12	13	14
Final PCN Issue Date		X							
Qual Report Availability							X		
Estimated First Ship Date			X						

Method to Identify Change: Traceability code

Estimated Qualification Completion Date: March 2021

Note: This final PCN will be updated to include the Qualification report as soon as it is completed.

Revision History: February 9, 2021: Issued final notification. Provided estimated first ship date to be February 19, 2021.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_JAON-04DXFD964_Qual_Plan.pdf](#)

[PCN_JAON-04DXFD964_Pre and Post Change_Summary.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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